

BRLV10T100EQ

Rev.A Apr.-2022



DATA SHEET

/ Revised record

G	2018-10				
H	2020-10-26				
A	2022-4-23	all	BR/Q AEC-Q101 Q 245±5°C 0.5sec 5°C 5± 255± 5±0.5sec		

/ Descriptions

TO-277

TO-277 Plastic package Schottky diode .

/ Features

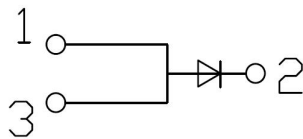
AEC-Q101

High Forward Surge Capability, Ultra Low Forward Voltage Drop,Excellent High Temperature Stability, Qualified to AEC-Q101 Standards for High Reliability, HF Product.

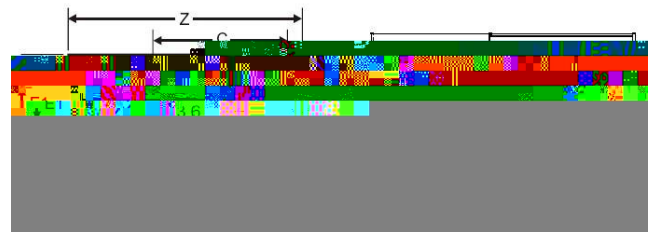
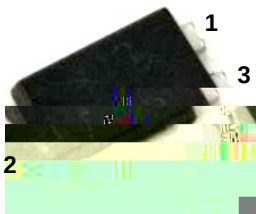
/ Applications

For use in low voltage, high frequency inverters, free wheeling, and polarity protection applications, Meet the stringent requirements of automotive applications.

/ Equivalent Circuit



/ Pinning



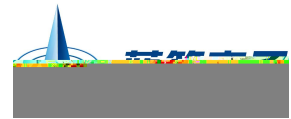
PIN1 Anode PIN 2 Cathode PIN 3 Anode

Suggested Pad layout

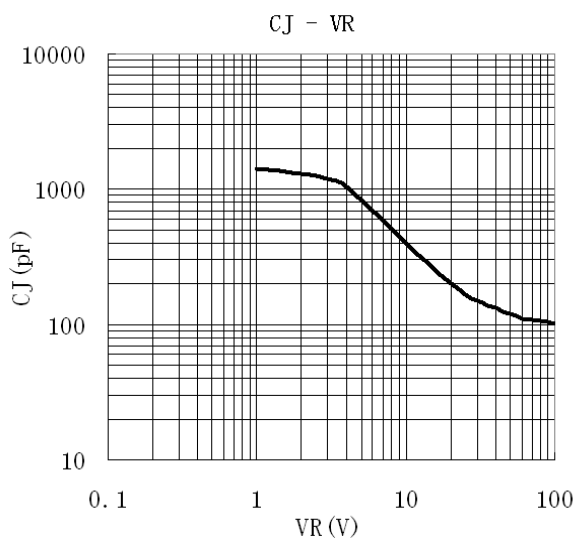
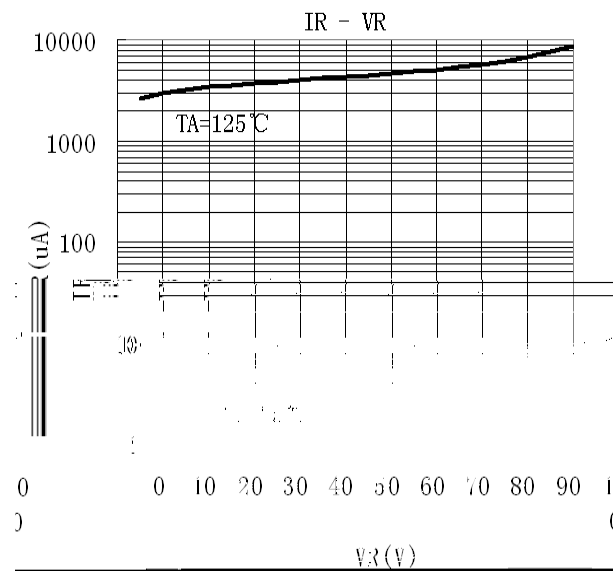
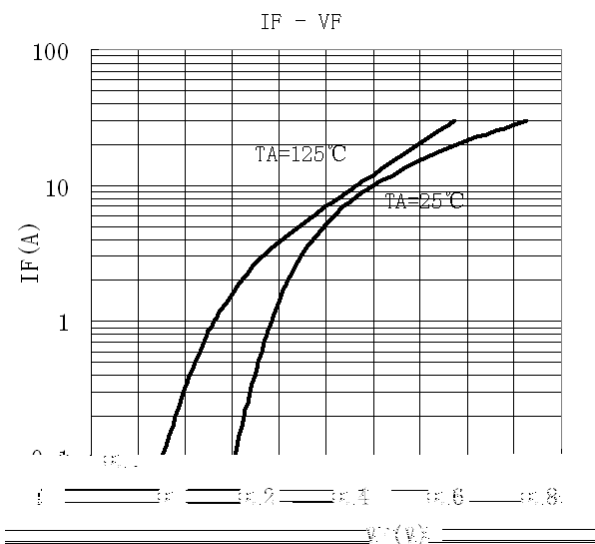
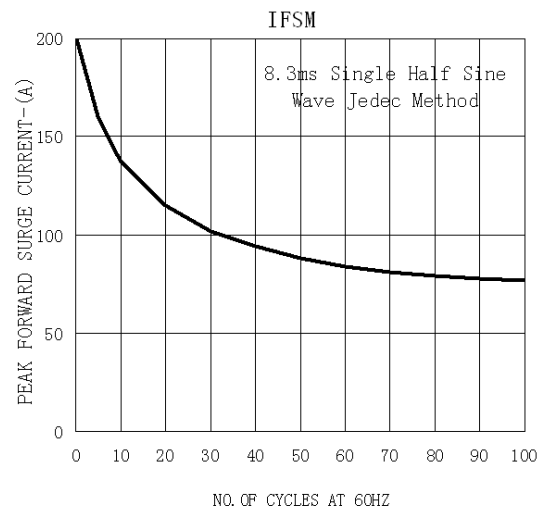
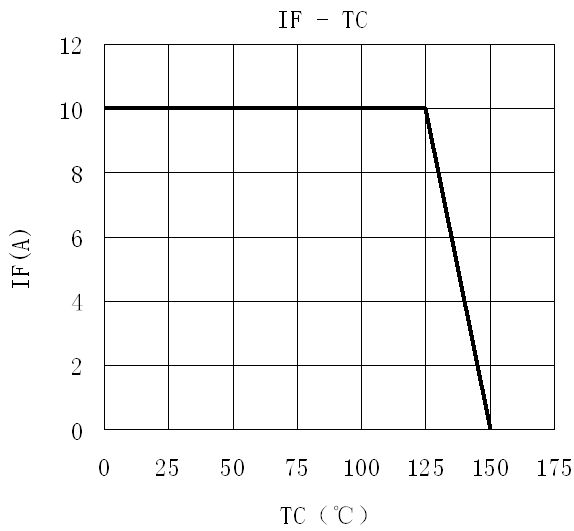
/ Marking

See Marking Instructions.

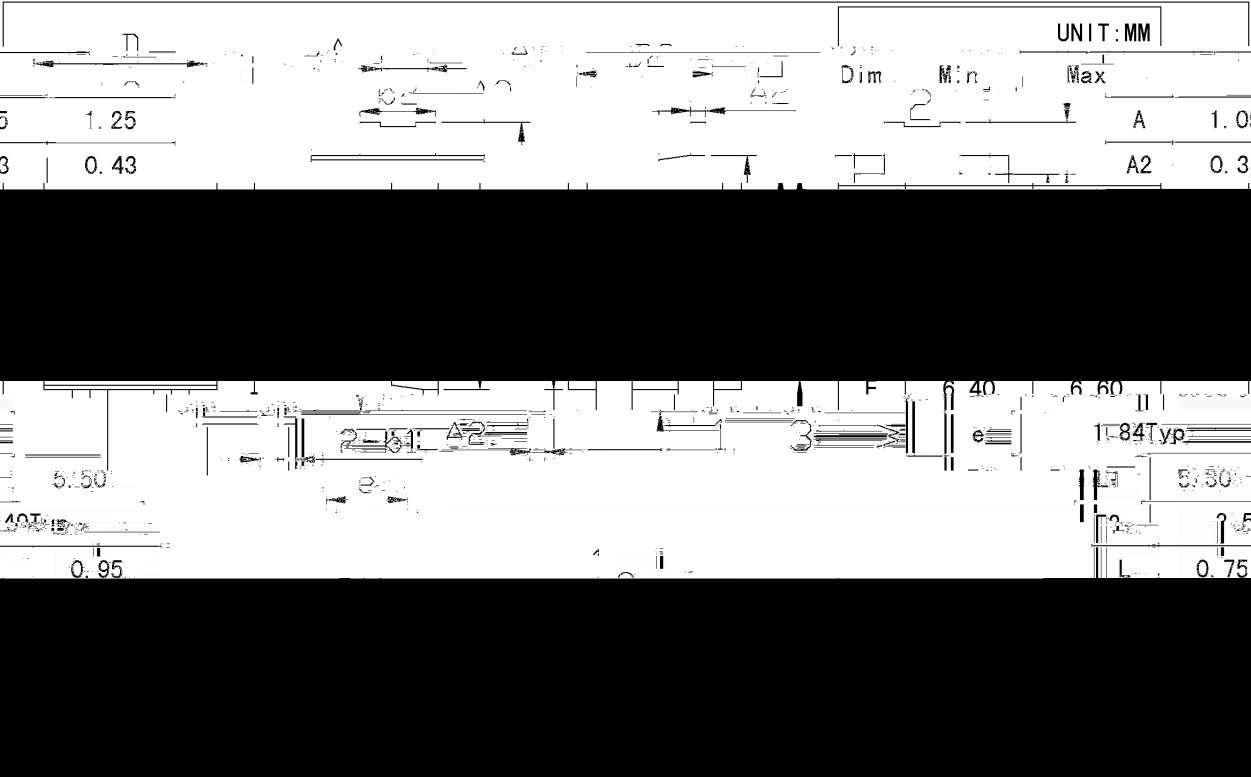
BRLV10T100EQ



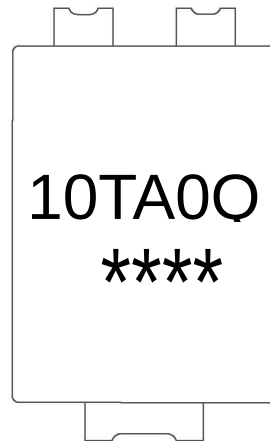
/ Electrical Characteristic Curve



/ Package Dimensions



/ Marking Instructions



说明：

10TA0：为型号代码

Q：为汽车无卤产品标识

****：为生产批号代码，随生产批号变化

Note:

10TA0：Product Type

Q: Automobile halogen-free product Code

****: Lot No. Code, code change with Lot No

() / Temperature Profile for IR Reflow Soldering(Pb-Free)

Note:

- | | | | |
|---|-------------|------------|--|
| 1 | 150 200 | 60 120sec; | 1.Preheating:150~200°C, Time:60~120sec. |
| 2 | 255±5 | 5±0.5sec; | 2.Peak Temp.:255±5°C, Duration:5±0.5sec. |
| 3 | 2 10°C/sec. | | 3. Cooling Speed: 2~10°C/sec. |

/ Resistance to Soldering Heat Test Conditions

260±5°C	10±1 sec.	Temp.:260±5°C	Time:10±1 sec
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/ Packaging SPEC.

/ REEL

Package Type	Units	Dimension	(unit mm ³)
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